

ABSTRACT

A wiring substrate, in which a wiring stacked portion including a conductor layer and a resin layer is stacked on a principal face of a core substrate including a substantially cylindrical through hole conductor in a through hole extending therethrough and a filling material filling a hollow portion of said through hole, comprising: a cover-shaped conductor portion covering an end face of said through hole just above a principal face of said core substrate and connected to said through hole conductor; and a terminal pad conductor provided over a principal face of said wiring stacked portion for disposing connection terminals used for connections with an external device, wherein a connection portion composed of via conductors buried in said resin layer brings said cover-shaped connection portion and said terminal pad conductor into conduction, and said via conductors composing said connection portion are provided not above a center axis of said through hole.